

WHAT IS CLAIMED IS:

1. A non-volatile semiconductor memory device comprising:
a first basic memory block having a plurality of memory cells
arranged in a matrix and having a first storage capacity corresponding to a
unit of collective erasure, said collective erasure not allowed in a partial
5 region of said first basic memory block, said partial region of said first basic
memory block having a second storage capacity smaller than said first
storage capacity;
a plurality of second basic memory blocks provided independent of
10 said first basic memory block, each having a plurality of memory cells
arranged in a matrix and each having said second storage capacity, a total
storage capacity of said plurality of second basic memory blocks being equal
to said first storage capacity; and
an erasure control circuit switching, in accordance with a switching
15 signal, between a first operation of erasing one of said plurality of second
basic memory blocks in accordance with an erasure command, and a second
operation of erasing said plurality of second basic memory blocks collectively
in accordance with said erasure command.
2. The non-volatile semiconductor memory device according to
claim 1, wherein at least one of said plurality of second basic memory blocks
includes a boot block read at a start of a system in which said non-volatile
semiconductor memory device is used.
3. The non-volatile semiconductor memory device according to
claim 1, wherein at least one of said plurality of second basic memory blocks
includes a memory block for programming data that is expected to be
rewritten more frequently than data to be programmed into said first basic
5 memory block.
4. The non-volatile semiconductor memory device according to
claim 1, further comprising:

a lead supplying a predetermined fixed potential; and
a pad to switch a polarity of said switch signal with respect to said
5 erasure control circuit,
wherein said erasure control circuit includes a select signal
generation circuit setting said switch signal at a first polarity when wire
bonding is established between said lead and said pad.

5. The non-volatile semiconductor memory device according to
claim 1, wherein said erasure control circuit comprises a switch signal
generation circuit providing said switch signal,
said switch signal generation circuit includes a non-volatile storage
5 element to determine said switch signal in accordance with stored contents.

6. The non-volatile semiconductor memory device according to
claim 5, wherein said non-volatile storage element is a fuse element
determining said switch signal in accordance with absence/presence of
connection.

7. The non-volatile semiconductor memory device according to
claim 5, wherein said non-volatile storage element has a structure identical
to the structure of a non-volatile memory cell included in said first and
second basic memory blocks.

8. The non-volatile semiconductor memory device according to
claim 1, wherein said erasure control circuit selects said plurality of second
basic memory blocks together when a pulse is to be applied collectively to a
plurality of non-volatile memory cells in the case of said second operation.

9. The non-volatile semiconductor memory device according to
claim 1, wherein said erasure control circuit sequentially selects said
plurality of second basic memory blocks, and initiates an erasure operation
of a subsequent basic memory block of a selected basic memory block after
5 erasure of said selected basic memory block is completed in the case of said

second operation.

10. The non-volatile semiconductor memory device according to claim 1, wherein said plurality of second basic memory blocks and said first basic memory block are allocated a predetermined address region,
said plurality of second basic memory blocks are arranged at a most
5 significant side of said predetermined address region.

11. The non-volatile semiconductor memory device according to claim 1, wherein said plurality of second basic memory blocks and said first basic memory block are allocated a predetermined address region,
said plurality of second basic memory blocks are arranged at a least
5 significant side of said predetermined address region.

12. The non-volatile semiconductor memory device according to claim 1, further comprising a plurality of third basic memory blocks corresponding to a unit of collective erasure, each third basic memory block having a storage capacity smaller than the storage capacity of said first
5 basic memory block, wherein
said plurality of third basic memory blocks, said plurality of second basic memory blocks, and said first basic memory block are allocated a predetermined address region, and
one of said plurality of second basic memory blocks and said
10 plurality of third basic memory blocks are arranged at a most significant side in said predetermined address region, and the other of said plurality of second basic memory blocks and said plurality of third basic memory blocks are arranged at a least significant side of said predetermined address region.

13. A non-volatile semiconductor memory device comprising:
a first basic memory block having a plurality of memory cells arranged in a matrix and having a first storage capacity corresponding to a unit of collective erasure, said collective erasure not allowed in a partial

5 region of said first basic memory block, said partial region of said first basic memory block having a second storage capacity smaller than said first storage capacity;

a plurality of second basic memory blocks provided independent of said first basic memory block, each having a plurality of memory cells
10 arranged in a matrix and each having said second storage capacity, a total storage capacity of said plurality of second basic memory blocks being equal to said first storage capacity; and

an erasure control circuit switching, in accordance with a switch signal, between a first operation of erasing one of said plurality of second
15 basic memory blocks in accordance with an erasure command, and a second operation of erasing said first basic memory block in accordance with said erasure command.

14. The non-volatile semiconductor memory device according to claim 13, further comprising:

a lead providing a predetermined fixed potential; and
a pad to switch a polarity of said switch signal with respect to said
5 erasure control circuit,

wherein said erasure control circuit includes a switch signal generation circuit setting said switch signal at a first polarity when wire bonding is established between said lead and said pad.

15. The non-volatile semiconductor memory device according to claim 13, wherein said erasure control circuit includes a switch signal generation circuit providing said switch signal,

said switch signal generation circuit includes a non-volatile storage
5 element to determine said switch signal in accordance with stored content.

16. The non-volatile semiconductor memory device according to claim 15, wherein said non-volatile storage element includes a fuse element determining said switch signal in accordance with absence/presence of connection.

17. The non-volatile semiconductor memory device according to claim 15, wherein said non-volatile storage element has a configuration identical to the configuration of a non-volatile memory cell included in said first and second basic memory blocks.

18. The non-volatile semiconductor memory device according to claim 13, wherein said plurality of second basic memory blocks and said first basic memory block are allocated a predetermined address region,

5 said plurality of second basic memory blocks are arranged at a most significant side of said predetermined address region.

19. The non-volatile semiconductor memory device according to claim 13, wherein said plurality of second basic memory blocks and said first basic memory block are allocated a predetermined address region,

5 said plurality of second basic memory blocks are arranged at a most significant side of said predetermined address region.

20. The non-volatile semiconductor memory device according to claim 13, further comprising a plurality of third basic memory blocks corresponding to a unit of collective erasure, each third basic memory block having a storage capacity smaller than the storage capacity of said first basic memory block, wherein

5 said plurality of third basic memory block, said plurality of second basic memory blocks, and said first basic memory block are allocated a predetermined address region, and

10 one of said plurality of second basic memory blocks and said plurality of third basic memory blocks are arranged at a most significant side of said predetermined address region, and the other of said plurality of second basic memory blocks and said plurality of third basic memory blocks are arranged at a least significant side of said predetermined address region.